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LISTING OF CLAIMS

The following listing of claims replaces all previous versions, and listings, of claims in the present invention.

1. (Currently amended) A semiconductor dynamic sensor comprising:

a semiconductor sensor chip having a member movable according to a dynamic force applied thereto, the semiconductor sensor chip outputting a sensor signal in response to an amount of movement of the movable ~~member;~~ member, the movable member being provided on one surface of the semiconductor sensor chip; and

a substrate for mounting and supporting the semiconductor sensor chip thereon, ~~wherein;~~ wherein the other surface of the semiconductor sensor chip is connected to the substrate via an adhesive film.

2. (Original) The semiconductor dynamic sensor as in claim 1, further including a package case, wherein:

the substrate is a semiconductor chip having a circuit for processing the sensor signal;

the semiconductor sensor chip is connected to a first surface of the semiconductor chip having the processing circuit; and

a second surface of the semiconductor chip having the processing circuit is partially connected to the package case.

3. (Original) The semiconductor dynamic sensor as in claim 1, wherein:

the adhesive film is made of a thermosetting resin or a thermoplastic resin.

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4. (Original) The semiconductor dynamic sensor as in claim 3, wherein:

a thickness of the adhesive film is less than 50 μm .

5. (Previously presented) The semiconductor dynamic sensor as in claim 3, wherein:

an elasticity coefficient of the adhesive film is less than 3,000 mega Pascals.

6. (Original) The semiconductor dynamic sensor as in claim 1, wherein:

the semiconductor sensor chip is a sensor chip for sensing acceleration.

7-8. (Canceled)

9. (Currently amended) A semiconductor dynamic sensor, comprising:

a substrate;

a sensor chip, including a movable member for sensing a dynamic force applied thereto, for generating sensor signals proportional to an amount of movement of the movable member; member, the movable member being provided on one surface of the sensor chip; and

a film located between the substrate and the sensor chip for bonding a-the other surface of the sensor chip with a surface of the substrate.

10. (Previously presented) The semiconductor dynamic sensor of claim 9, wherein the substrate comprises a circuit chip electrically connected to the sensor chip for processing the sensor signals generated by the sensor chip.

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11. (Previously presented) The semiconductor dynamic sensor of claim 9, wherein the film comprises one of a thermosetting and a thermoplastic resin film.

12. (Previously presented) A semiconductor dynamic sensor comprising:

a substrate;

a sensor chip having a first surface and a second surface, the sensor chip including a movable member provided on the first surface for sensing a dynamic force applied thereto and for generating sensor signals in response to movement of the movable member; and

an adhesive film located between the substrate and the second surface of the sensor chip for bonding the second surface of the sensor chip with a surface of the substrate.

13. (Previously presented) The semiconductor dynamic sensor as in claim 12, further including a package case, wherein:

the substrate is a semiconductor chip having a processing circuit for processing the sensor signals;

the sensor chip is connected to a first surface of the semiconductor chip having the processing circuit; and

a second surface of the semiconductor chip having the processing circuit is partially connected to the package case.

14. (Previously presented) The semiconductor dynamic sensor as in claim 12, wherein the adhesive film is made of a thermosetting resin or a thermoplastic resin.

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15. (Previously presented) The semiconductor dynamic sensor as in claim 14, wherein a thickness of the adhesive film is less than 50 μm .

16. (Previously presented) The semiconductor dynamic sensor as in claim 14, wherein an elasticity coefficient of the adhesive film is less than 3,000 mega Pascals.

17. (Currently amended) ~~The semiconductor dynamic sensor as in 14, wherein A~~
semiconductor dynamic sensor comprising:

a substrate;

a sensor chip having a first surface and a second surface and including a movable member provided on the first surface for sensing a dynamic force applied thereto and for generating sensor signals in response to movement of the movable member; and

an adhesive film located between the substrate and the second surface of the sensor chip for bonding the second surface of the sensor chip with a surface of the substrate, wherein

the adhesive film is made of a thermosetting resin or a thermoplastic resin
and the adhesive film is further for providingprovides a temperature-dependency of sensor offset outputs that is less than or equal to 50 mV.

18. (Previously presented) The semiconductor dynamic sensor as in claim 12, wherein the sensor chip is for sensing acceleration.

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19. (New) The semiconductor dynamic sensor as in claim 17, wherein a thickness of the adhesive film is less than 50 μm .

20. (New) The semiconductor dynamic sensor as in claim 17, wherein an elasticity coefficient of the adhesive film is less than 3,000 mega Pascals.